

Half-Duplex RS-485/RS-422 Transceivers in μ DFN

■ Description

The TK13485E+5V, half-duplex, $\pm 15\text{kV}$ ESD-protected RS-485 transceivers feature one driver and one receiver. The device includes fail-safe circuitry, guaranteeing a logic-high receiver output when receiver inputs are open or shorted. The receiver outputs a logic-high if all transmitters on a terminated bus are disabled (high impedance). The TK13485E include a hot-swap capability to eliminate false transitions on the bus during power-up or live-insertion. The TK13485E features a 1/4-unit load receiver input impedance, allowing up to 128 transceivers on the bus. It is intended for half-duplex communications. It is available in 8-pin SOIC packages.

■ Features

- 1 transmitter and 1 receivers of the serial data of the standard RS-485
- Hot-Swappable for Telecom Applications
- 5V Supply Voltage Range
- Operating temperature range: $-40 \sim +85\text{ }^{\circ}\text{C}$
- Data rate: 500kbps
- Low $10\mu\text{A}$ (max) Shutdown Current for Lower Power Consumption
- Allows Up to 128 Transceivers on the Bus
- Enhanced ESD Specifications:
 $\pm 15\text{kV}$ Extended ESD Protection

■ Ordering Information

Part Number	Package	Packing	Temperature(TA)	Package Qty	ESD
TK13485EESA	SOIC-8	Reel	$-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$	2500	$\pm 15\text{KV}$

Note: Please contact us to customize DIP packaging device.

■ Pin Description

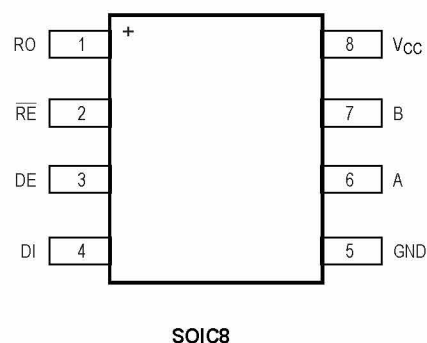


Table 1. Pin Description

PIN	NAME	FUNCTION
1	RO	Receiver Output.
2	\overline{RE}	Receiver Output Enable. Drive \overline{RE} low to enable RO. Drive \overline{RE} high to disable the receiver. RO is high impedance when \overline{RE} is high. Drive \overline{RE} high and pull DE low to enter low-power shutdown mode.
3	DE	Driver Output Enable. Drive DE high to enable the driver. Drive DE low to disable the driver. Driver outputs are high-impedance when the driver is disabled. Drive \overline{RE} high and pull DE low to enter low-power shutdown mode.
4	DI	Driver Input. Drive DI low to force noninverting output low and inverting output high. Drive DI high to force noninverting output high and inverting output low
5	GND	Ground
6	A	Noninverting RS-485/RS-422 Receiver Input and Driver Output
7	B	Inverting RS-485/RS-422 Receiver Input and Driver Output
8	V _{CC}	Positive Supply. V _{CC} = +5V ±5%. Bypass V _{CC} with a 0.1 μF ceramic capacitor to ground.

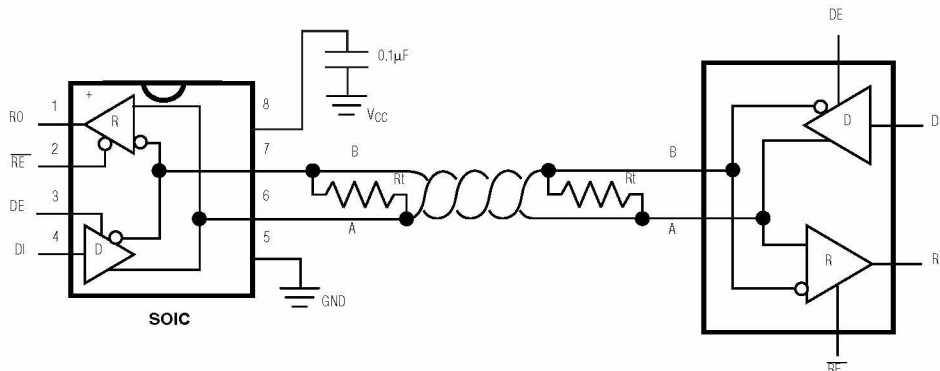
Functional Diagram


Table 2. Function Tables Transmitter Truth Table

TRANSMITTING					
INPUTS			OUTPUTS		MODE
\overline{RE}	DE	DI	B	A	
X	H	H	L	H	Active
X	H	L	H	L	Active
L	L	X	High Impedance		Driver Disabled
H	L	X	High Impedance		Shutdown

Note : H – high level, L – low level , X –don't care, Z – third state

Table 3. Function Tables Receiver Truth Table

RECEIVING				
INPUTS			OUTPUTS	MODE
\overline{RE}	DE	A-B	RO	
L	X	$\geq -50mV$	H	Active
L	X	$\leq -200mV$	L	Active
L	X	Open/Shorted	H	Active
H	H	X	High Impedance	Receiver Disabled
H	L	X	High Impedance	Shutdown

Note : H – high level, L – low level , BH – inputs not used, X –don't care, Z – third state,
 ZZ – inputs and outputs are in the third state

Table 4. Recommended Operating Condition

Symbol	Parameter	Limit		Unit
		min	max	
V_{CC}	Supply voltage	4.75	5.25	V
V_{IL}	Input low voltage DI, DE, \overline{RE} pins	0	0.8	V
V_{IH}	Input high voltage DI, DE, \overline{RE} pins	2.0	V_{CC}	V
V_{OD}	Transmitter output voltage	-7.0	12.0	V
V_{IR}	Receiver input voltage	-7.0	12.0	V
V_{OR}	Receiver output voltage	0	V_{CC}	V
V_{TH}	Receiver differential threshold voltage	$ \pm 50 $	$ \pm 200 $	V
T	Ambient temperature	-40	120	°C

Table 5. Maximum Ratings

Symbol	Parameter	Limit		Unit
		min	max	
V_{CC}	Supply voltage	-0.3	6.0	V
V_{IL}	Input voltage on pins DI, DE, \overline{RE}	-0.3	6.0	V
V_{OD}	Transmitter output voltage	-8	13	V
V_{IR}	Receiver input voltage	-8	13	V
V_{OR}	Receiver output voltage	-0.3	$V_{CC}+0.3$	V

* Stresses beyond those listed under “maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Table 6. Electrical Parameters

(V_{CC} = +5V ±5%, T_A = T_{MIN} to T_{MAX}, Typical values are at V_{CC} = +5V and T_A = +25°C.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DRIVER						
Differential Driver Output	V _{OD}	R _{DIFF} = 100Ω, Figure 1	2.0	V _{CC}		V
		R _{DIFF} = 54Ω, Figure 1	1.5			
		No load		V _{CC}		
Change in Magnitude of Differential Output Voltage	ΔV _{OD}	R _{DIFF} = 100Ω or 54Ω, Figure 1 (Note 1)		0.2		V
Driver Common-Mode Output Voltage	V _{OC}	R _{DIFF} = 100Ω or 54Ω, Figure 1		V _{CC} / 2	3	V
Change in Magnitude of Common-Mode Voltage	ΔV _{OC}	R _{DIFF} = 100Ω or 54Ω, Figure 1 (Note 1)		0.2		V
Input-High Voltage	V _{IH}	DI, DE, \overline{RE}	2.0			V
Input-Low Voltage	V _{IL}	DI, DE, \overline{RE}		0.8		V
Input Current	I _{IN}	DI, DE, \overline{RE}		±1		μA
Driver Short-Circuit Output Current (Note 2)	I _{OSD}	0V ≤ V _{OUT} ≤ +12V	+50	+250		mA
		-7V ≤ V _{OUT} ≤ 0V	-250	-50		
Driver Short-Circuit Foldback Output Current Note 1)	I _{OSDF}	(V _{CC} - 1V) ≤ V _{OUT} ≤ +12V	20			mA
		-7V ≤ V _{OUT} ≤ 0V		-20		
RECEIVER						
Input Current (A and B)	I _{A, B}	DE = GND, V _{CC} = GND or +5V	V _{IN} = +12V		250	μA
			V _{IN} = -7V	-200		
Receiver-Differential-Threshold Voltage	V _{TH}	-7V ≤ V _{CM} ≤ +12V	-200	-50		mV
Receiver Input Hysteresis	ΔV _{TH}	V _A + V _B = 0V		25		mV
Output-High Voltage	V _{OH}	I _O = -1.6mA, V _A - V _B > V _{TH}		V _{CC} - 1.5		V
Output-Low Voltage	V _{OL}	I _O = 1mA, V _A - V _B < -V _{TH}		0.4		V
Tri-State Output Current at Receiver	I _{OZR}	0V ≤ V _O ≤ V _{CC}		±1		μA
Receiver Input Resistance	R _{IN}	-7V ≤ V _{CM} ≤ +12V	48			kΩ
Receiver-Output Short-Circuit Current	I _{OSR}	0V ≤ V _{RO} ≤ V _{CC}	±7	±95		mA
POWER SUPPLY						
Supply Voltage	V _{CC}		4.75	5.25		V
Supply Current	I _{CC}	DE = 1, \overline{RE} = 0, no load		4.5		mA
Shutdown Supply Current	I _{SHDN}	DE = 0, \overline{RE} = 1		10		μA
ESD PROTECTION						
ESD Protection (A, B)		Air Gap Discharge IEC61000-4-2 (MAX13485E)		±15		kV
		Human Body Model		±15		
ESD Protection (All Other Pins)		Human Body Model		±2		kV

Table 7. Switching Characteristics

($V_{CC} = +5V \pm 5\%$, $T_A = T_{MIN}$ to T_{MAX} , . Typical values are at $V_{CC} = +5V$ and $T_A = +25^\circ C$.)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
DRIVER						
Driver Propagation Delay	t_{DPLH}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$, Figures 2 and 3	200		1000	ns
	t_{DPHL}		200		1000	
Driver-Differential Output Rise or Fall Time	t_{HL}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$, Figures 2 and 3	250		900	ns
	t_{LH}		250		900	
Driver-Differential Output Skew ($t_{DPLH} - t_{DPHL}$)	t_{DSKEW}	$R_{DIFF} = 54\Omega$, $C_L = 50pF$, Figures 2 and 3			140	ns
Maximum Data Rate			500			kbps
Driver Enable to Output High	t_{DZH}	Figures 4 and 5			2500	ns
Driver Enable to Output Low	t_{DZL}	Figures 4 and 5			2500	ns
Driver Disable Time from High	t_{DZH}	Figures 4 and 5			100	ns
Driver Disable Time from Low	t_{DLZ}	Figures 4 and 5			100	ns
Driver Enable from Shutdown to Output High	$t_{DZH}(SHDN)$	Figures 4 and 5			5500	ns
Driver Enable from Shutdown to Output Low	$t_{DZL}(SHDN)$	Figures 4 and 5			5500	ns
Time to Shutdown	t_{SHDN}		50	340	700	ns
RECEIVER						
Receiver Propagation Delay	t_{RPLH}	$C_L = 15pF$, Figures 6 and 7			80	ns
	t_{RPHL}				80	
Receiver Output Skew	t_{RSKEW}	$C_L = 15pF$, Figure 7			13	ns
Maximum Data Rate			500			kbps
Receiver Enable to Output High	t_{RZH}	Figure 8			50	ns
Receiver Enable to Output Low	t_{RZL}	Figure 8			50	ns
Receiver Disable Time from High	t_{RHZ}	Figure 8			50	ns
Receiver Disable Time from Low	t_{RLZ}	Figure 8			50	ns
Receiver Enable from Shutdown to Output High	$t_{RZH}(SHDN)$	Figure 8			2200	ns
Receiver Enable from Shutdown to Output Low	$t_{RZL}(SHDN)$	Figure 8			2200	ns
Time to Shutdown	t_{SHDN}		50	340	700	ns

Note 1: ΔV_{OD} and ΔV_{OC} are the changes in V_{OD} and V_{OC} when the DI input changes states.

Note 2: The short-circuit output current applied to peak current just prior to foldback current limiting. The short-circuit foldback output current applies during current limiting to allow a recovery from bus contention.

Test and Timing Diagrams

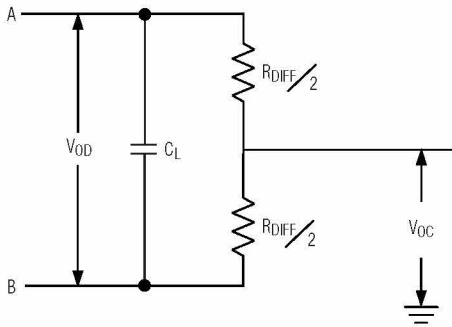


Figure 1. Driver DC Test Load

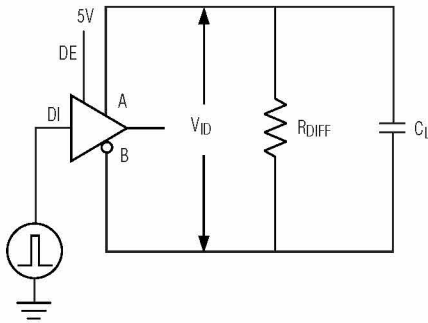


Figure 2. Driver Timing Test Circuit

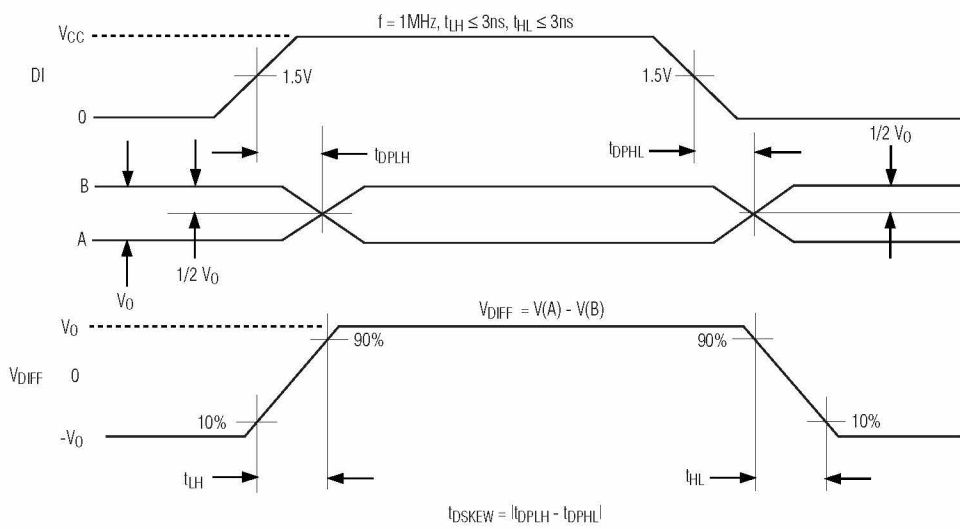


Figure 3. Driver Propagation Delays

Test and Timing Diagrams(continued)

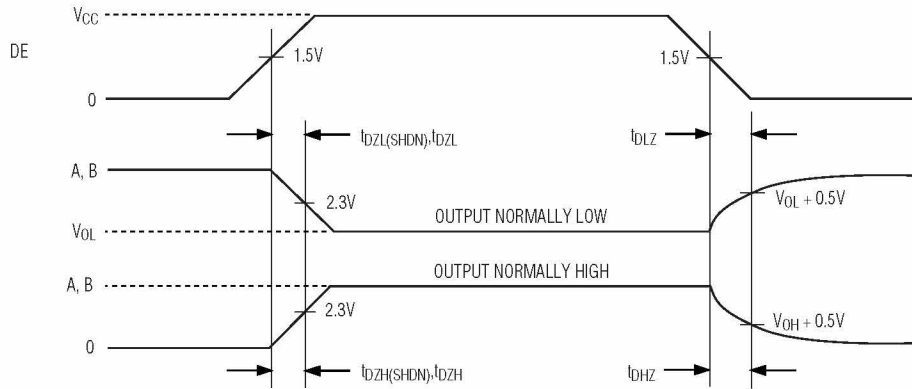


Figure 4. Driver Enable and Disable Times (t_{DZH} , t_{DLZ})

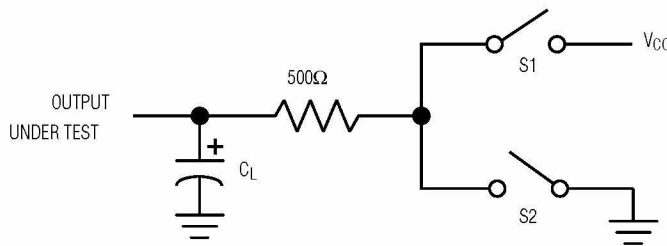


Figure 5. Driver Enable and Disable Times (t_{DZL} , t_{DLZ})

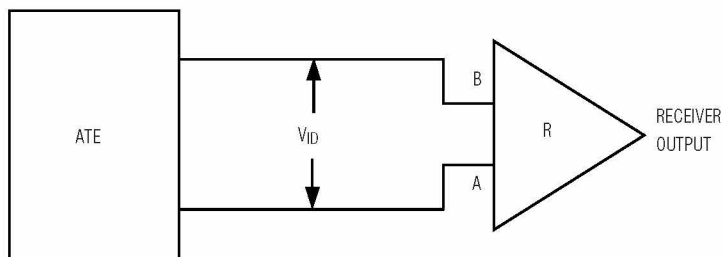


Figure 6. Receiver Propagation Delay Test Circuit

Test and Timing Diagrams(continued)

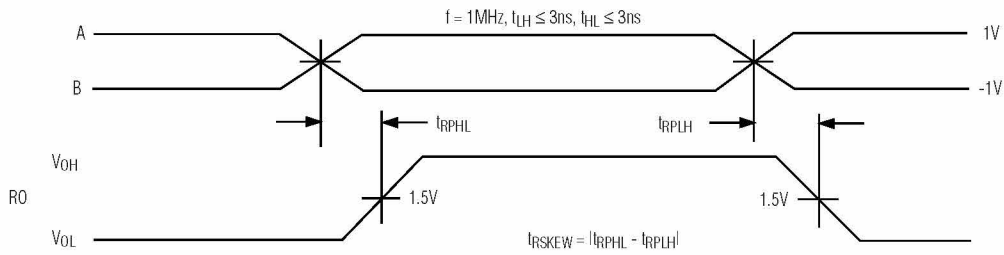


Figure 7. Receiver Propagation Delays

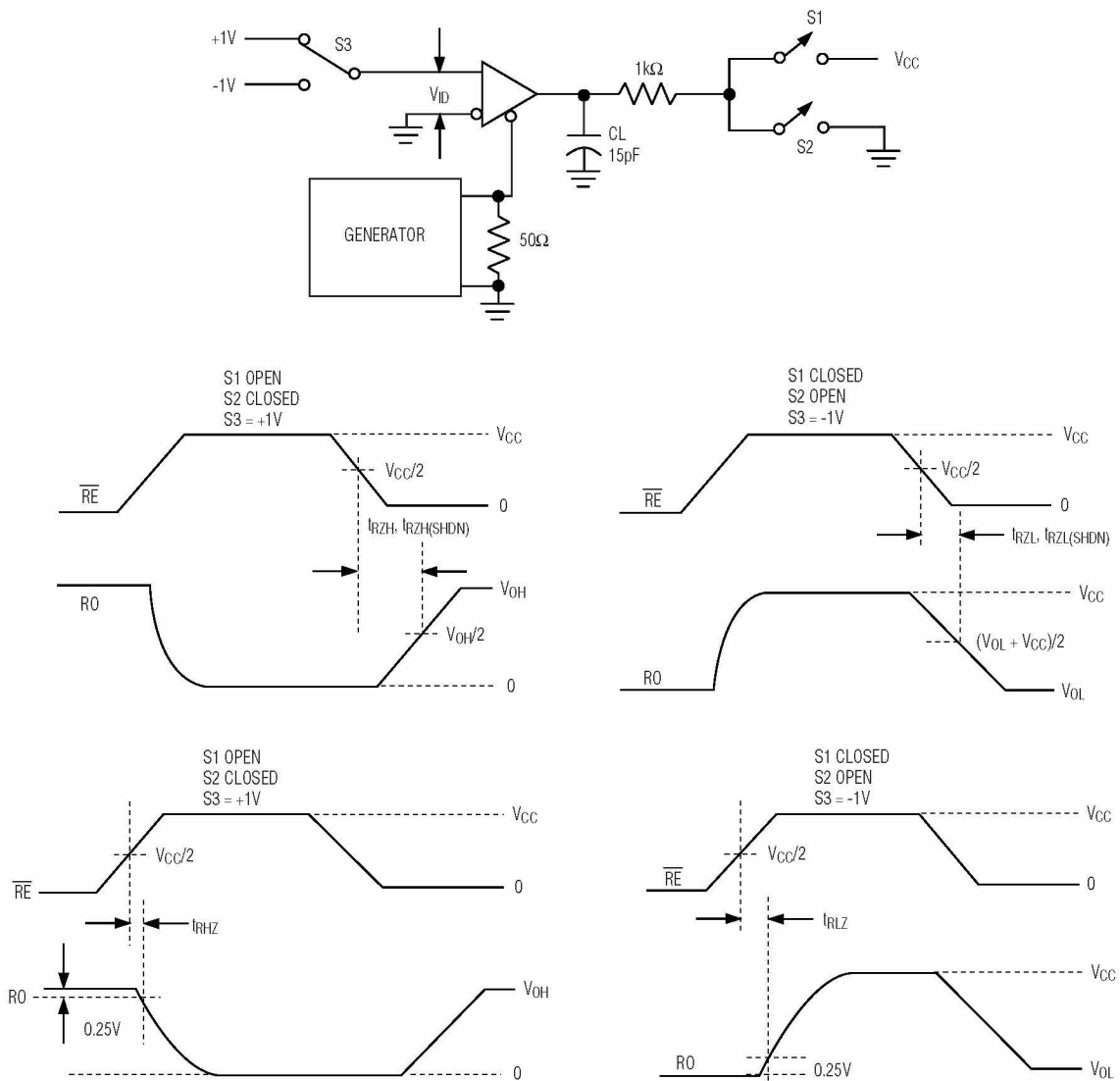
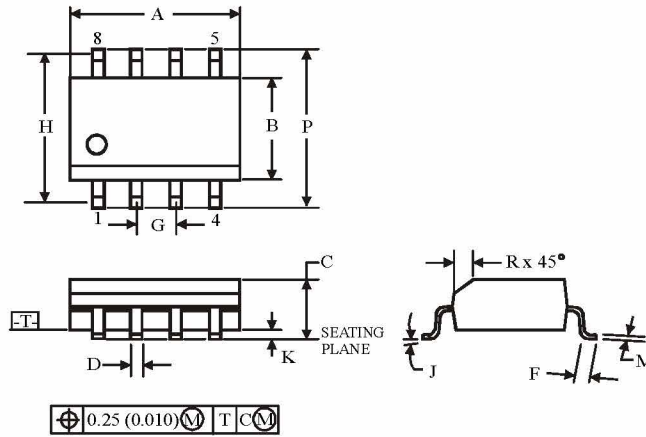


Figure 8. Receiver Enable and Disable Times

■ Package Dimensions
SOIC8


Symbol	Dimension, mm	
	MIN	MAX
A	4.8	5
B	3.8	4
C	1.35	1.75
D	0.33	0.51
F	0.4	1.27
G	1.27	
H	5.72	
J	0°	8°
K	0.1	0.25
M	0.19	0.25
P	5.8	6.2
R	0.25	0.5

NOTES:

1. Dimensions A and B do not include mold flash or protrusion.
2. Maximum mold flash or protrusion 0.15 mm (0.006) per side for A; for B - 0.25 mm (0.010) per side.